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FOR: NAME Examiner J. Lee
COMPANY Art Unit 2501
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Stephen B Maebius
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No. 50169/105/ENPO

In re patent application of

Wallace T.Y. TANG

Group Art Unit: 2501

Serial No. 08/401,229

Examiner: J. Lee

Filed: March 9, 1995

For: IN-SITU REAL-TIME MONITORING TECHNIQUE AND APPARATUS
FOR ENDPOINT DETECTION OF THIN FILMS DURING
CHEMICAL/MECHANICAL POLISHING PLANARIZATION

SUPPLEMENTAL AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Further to the Amendment filed on December 9, 1996, please
amend the above-identified application as follows:

IN THE CLAIMS

Please add the following claims:

31-76. An apparatus for chemical mechanical polishing of
a wafer, comprising

(a) a rotatable polishing platen with an overlying
polishing pad wetted with an abrasive slurry;

(b) a rotatable chuck for holding the wafer against the
polishing pad, the wafer comprising a semiconductor substrate
underlying an oxide layer; and

(c) and endpoint detector, comprising

(c1) a laser interferometer capable
of generating a laser beam
directed towards the wafer and
detecting light reflected from
the wafer, and

(c2) a hole formed through the
platen and polishing pad
allowing the laser beam to
reflect off a section of the

35